Abstracts

RF and mechanical characterization of flip-chip interconnects in CPW circuits with underfill (1998 Vol. III [MWSYM])

Zhiping Feng, Wenge Zhang, Bingzhi Su, K.C. Gupta and Y.C. Lee. "RF and mechanical characterization of flip-chip interconnects in CPW circuits with underfill (1998 Vol. III [MWSYM])." 1998 MTT-S International Microwave Symposium Digest 98.3 (1998 Vol. III [MWSYM]): 1823-1826.

RF characterization of flip-chip interconnects in CPW circuits with underfill has been investigated by measuring the scattering-parameters up to 40 GHz for GaAs coplanar waveguide (CPW) through line chips flip-chip mounted on alumina substrate with and without underfill epoxy. Fatigue life of flip-chip assemblies has been computed for different chip sizes and substrates. The results show feasibility of using underfill encapsulant in microwave/mm-wave frequency range.

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